



## Material Content Data Sheet



Halogen-Free

<b>Sales Product Name</b>	BSC027N10NS5	<b>Issued</b>	24. February 2022
<b>MA#</b>	MA005708854		
<b>Package</b>	PG-TSON-8-3	<b>Weight*</b>	123.95 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	2.913	2.35	2.35	23500	23500
leadframe	inorganic material	phosphorus	7723-14-0	0.009	0.01		73	
	non noble metal	zinc	7440-66-6	0.036	0.03		292	
	non noble metal	iron	7439-89-6	0.725	0.58		5849	
	non noble metal	copper	7440-50-8	29.440	23.75	24.37	237508	243722
wire	noble metal	gold	7440-57-5	0.053	0.04	0.04	429	429
encapsulation	organic material	carbon black	1333-86-4	0.093	0.07		748	
	plastics	epoxy resin	-	4.777	3.85		38540	
	inorganic material	silicondioxide	60676-86-0	41.511	33.49	37.41	334889	374177
leadfinish	non noble metal	tin	7440-31-5	1.343	1.08	1.08	10833	10833
plating	noble metal	silver	7440-22-4	0.030	0.02	0.02	244	244
solder	non noble metal	tin	7440-31-5	0.065	0.05		520	
	noble metal	silver	7440-22-4	0.081	0.07		651	
	non noble metal	lead	7439-92-1	3.080	2.49	2.61	24851	26022
heat sink clip	inorganic material	phosphorus	7723-14-0	0.009	0.01		77	
	non noble metal	iron	7439-89-6	0.032	0.03		255	
	non noble metal	copper	7440-50-8	31.570	25.47	25.51	254693	255025
heatspreader	inorganic material	phosphorus	7723-14-0	0.002			20	
	non noble metal	zinc	7440-66-6	0.010	0.01		79	
	non noble metal	iron	7439-89-6	0.196	0.16		1585	
	non noble metal	copper	7440-50-8	7.978	6.44	6.61	64364	66048
*deviation	< 10%	Sum in total:				100.00		1000000

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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